

line 8, before "strip" insert - -substrate- -;

line 9, before "strip" insert - -substrate- -;

line 15, before "strip" insert - -substrate- -;

line 17, after "substrate" insert - -strip- -;

line 20, before "strip" insert - -substrate- -;

line 21, before "strip" insert - -substrate- -;

line 23, before "strip" insert - -substrate- -;

line 24, before "strip" insert - -substrate- -;

line 25, before "strip" insert - -substrate- -;

line 26, before "strip" insert - -substrate- -;

line 28, before "strip" insert - -substrate- -;

line 29, before "strip" insert - -substrate- -.

Page 2, line 3, before "strip" insert - -substrate- -;

line 5, before "strips" insert - -substrate- -;

line 14, before "machine" insert - -sawing- -;

line 18, please cancel "cannot add to the peripheral substrate areas",
and insert - will not accumulate to the subsequent substrate areas or
substrate strips- -;

lines 19-20, please cancel "The present invention is a substrate sawing
process in accordance with an embodiment;" and insert - According to
the embodiment of the present invention- -;

line 20, after "includes" insert the steps of providing- -;

line 21, before "corresponding" insert - -marks- -;

line 21, before "strips" insert - -substrate- -;

line 24, before "strips" insert - -substrate- -;

line 28, please cancel "cannot add to the peripheral substrate areas" and
insert - will not accumulate to the subsequent substrate areas in the
substrate strip- -.

Page 3, line 18, please cancel "strip" and insert - substrate strip according to
prior art- -;

line 6, before "strip" insert - -substrate- -;

line 8, before "strip" insert - -substrate- -;

line 10, before "strip" insert - -substrate- -;

line 12, before "strip" insert - -substrate- -;

line 16, after "alignment" insert - -marks- -;

line 16, before "strip" insert - -substrate- -;

lines 22-23, please cancel "Substrate sawing process of the presenet invention is also mainly adapted to cut a strip or juxtaposed strips in the first phase and in the second phase."

lines 24-25, please cancel "the sawing process of the present invention in accordance with the first embodiment" and insert according to the first embodiment of the process for sawing substrate strip- -;

line 25, before "strip" insert - -substrate- -;

line 27, before "strip" insert - -substrate- -;

line 28, please cancel "is" and insert - -are- -.

Page 4, line 1, please cancel "is" and insert - -are- -;

line 4, please cancel "areas" and insert - -area- -;

line 5, before "strip" insert - -substrate- -;

lines 6-7, please cancel "utilizes a plurality of the cutting marks 112 to define the cutting tracks 101 in the first phase." and insert -is positioned with respect to each individual substrate area 110 according to the alignment marks 111 thereof and then the cutting tracks 101 in the first phase is defined by the cutting marks 112 on the substrate strip 100.- -;

Q9 line 11, please cancel "adding to the peripheral" and insert -from accumulating to the subsequent- -;

line 17, please cancel "It follows that" and insert - -Then- -;

line 18, before "strips" insert - -substrate- -;

Q10 line 20, after "substrate." insert -According to the preferred embodiment as shown in Fig. 2, the substrate strip 100 has a longitudinal axial and a lateral axial and the substrate areas 110 are disposed along the longitudinal axial, the saw machine is positioned with respect to the first substrate area 110 according to the alignment marks 111 along the longitudinal axial from the left and cuts the substrate strip 100 according to cutting tracks 101 defined by the cutting marks 112 parallel to the lateral axial. Then, the saw machine is positioned with respect to the second substrate area 110 from the left and then cuts the substrate strip 100. Therefore, the cutting error resulted from each substrate area 110 will not accumulate to the subsequent substrate areas in the substrate strip 100, thereby ensuring the cutting accuracy for the packaged substrate. Referring Fig. 3, after all substrate areas 110 are cut in the lateral direction of the substrate strip 100, the saw machine cuts the substrate strip 100 along the longitudinal axial thereof according to cutting tracks 101 defined by the cutting marks 112 parallel to the longitudinal axial.- -;

line 23, after "substrate" insert - -strip- -;

line 25, before "strips" insert - -substrate- -;

line 28, please cancel "strip in" and insert - -substrate strip having- -.